

Electronic Patent Application Fee Transmittal

Application Number:	10830188			
Filing Date:	21-Apr-2004			
Title of Invention:	Method for accommodating small minimum die in wire bonded area array packages			
First Named Inventor/Applicant Name:	Ryan Lane			
Filer:	Larry Jan Moskowitz/Pam Ly/WMH			
Attorney Docket Number:	020378D1			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Petition-revive unintent. abandoned appl	1453	1	1500	1500
Patent-Appeals-and-Interference:				
Filing a brief in support of an appeal	1402	1	500	500
Post-Allowance-and-Post-Issuance:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				2000